

# SOT2197-1(SC)

DLQFN12; Depopulated Low profile quad flat package, no leads; 12 terminals; 0.65 mm pitch; 3 mm x 3 mm x 1.25 mm body

20 March 2024

Package information



## 1 Package summary

<b>Package type descriptive code</b>	DLQFN12
<b>Package style descriptive code</b>	DLQFN (depopulated low profile quad flat package, no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	17-01-2024
<b>Manufacturer package code</b>	98ASA01979D

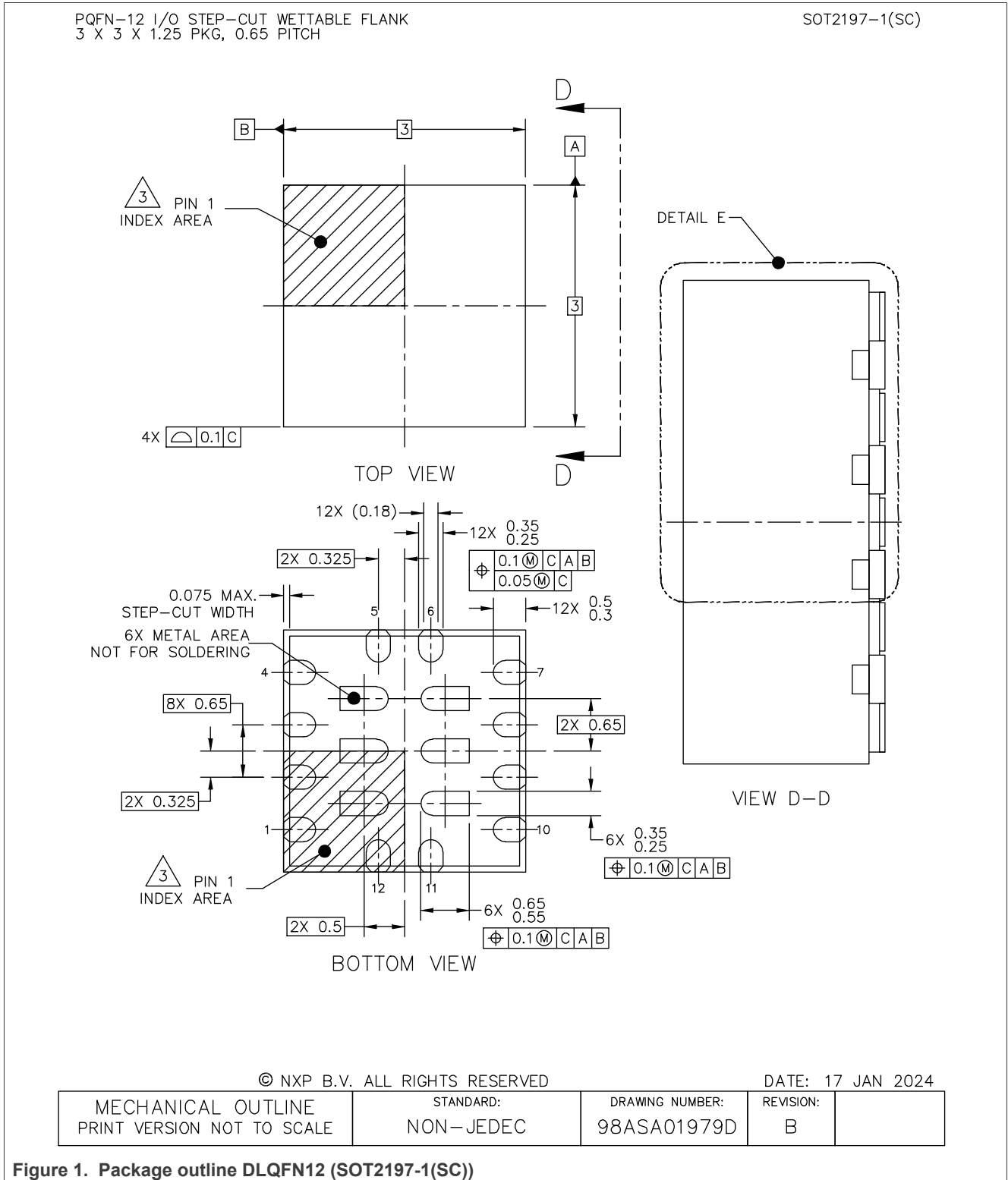
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	3	-	mm
package width	-	3	-	mm
seated height	-	1.25	-	mm

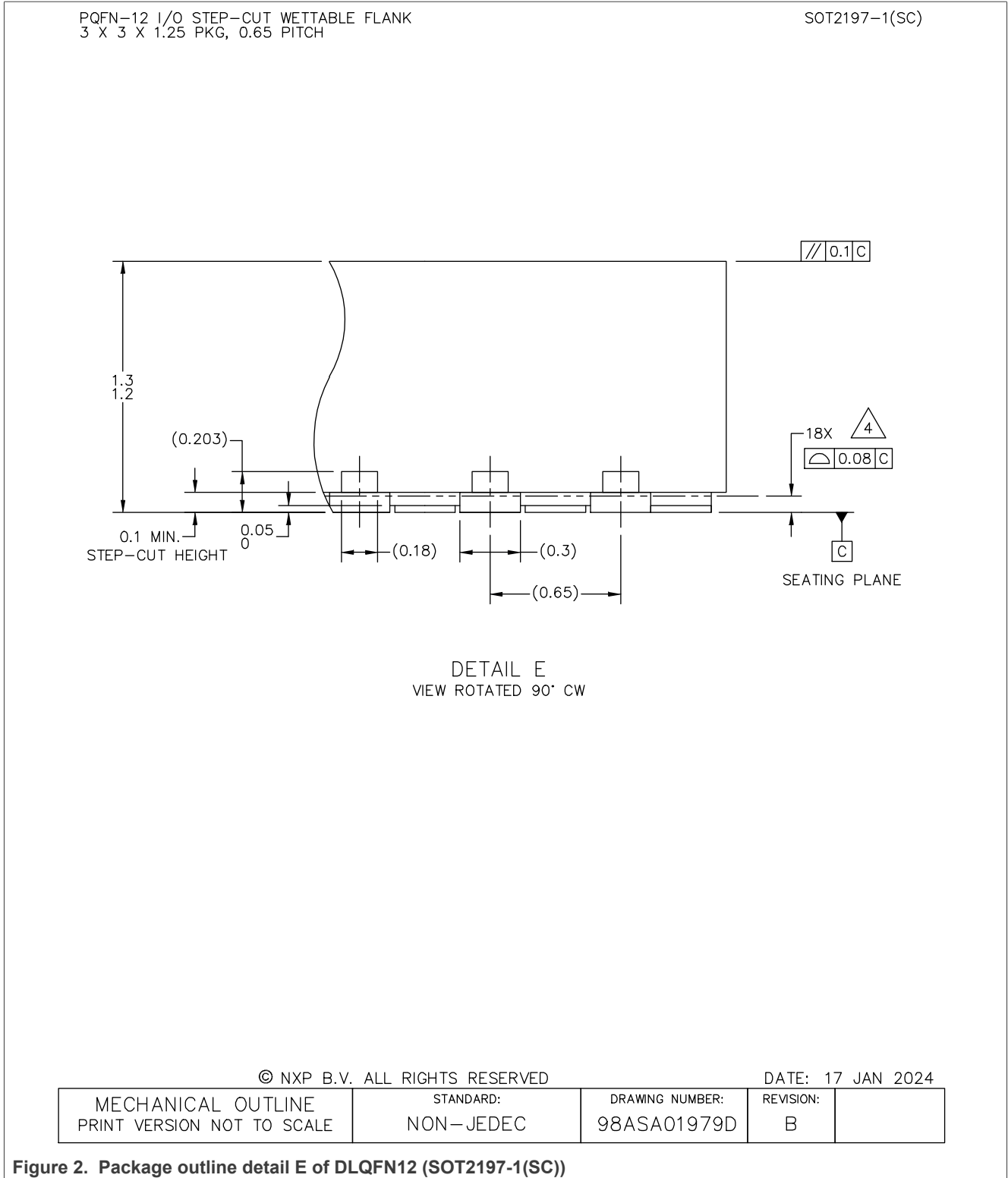


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2 Package outline



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3 Soldering

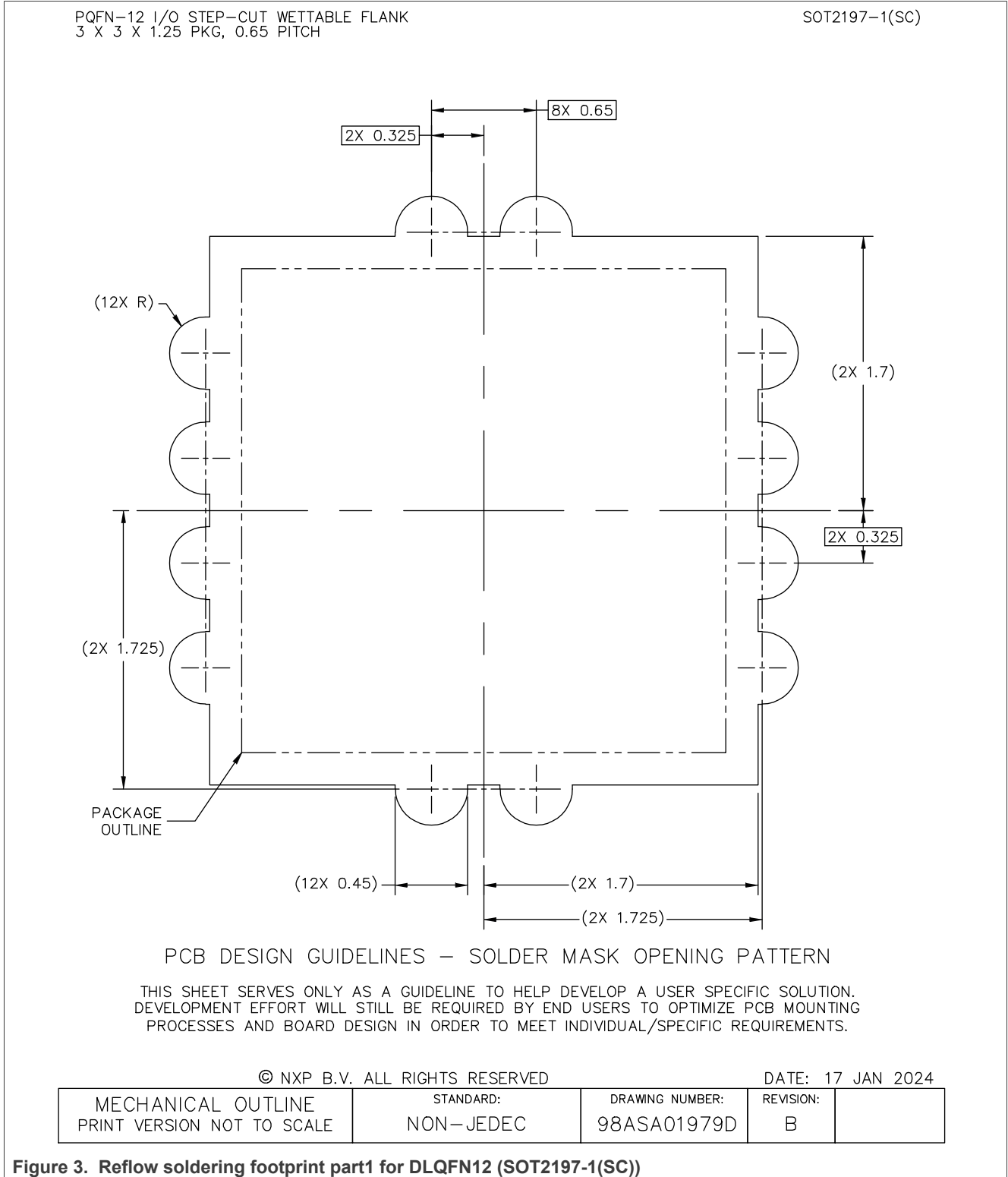
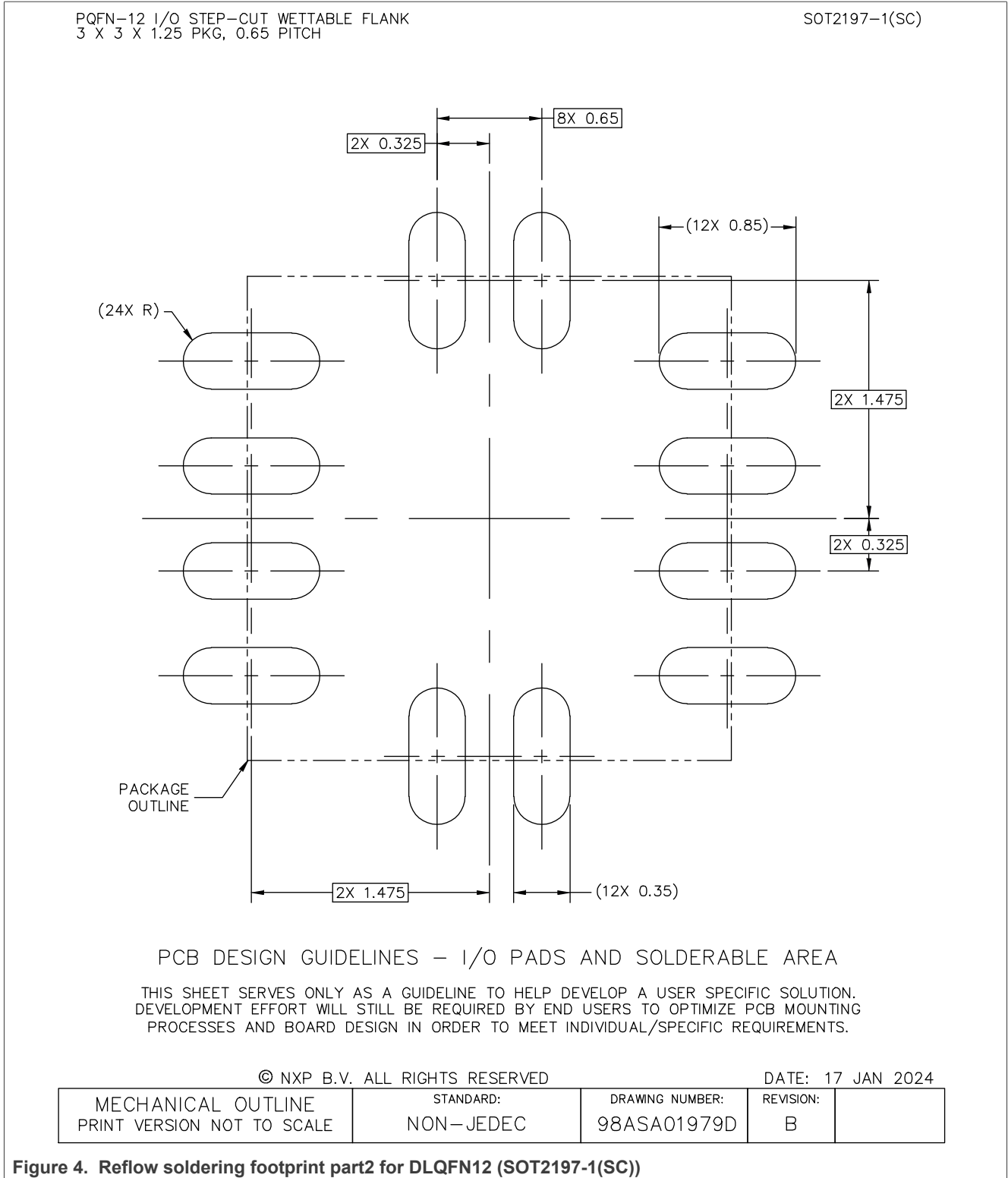
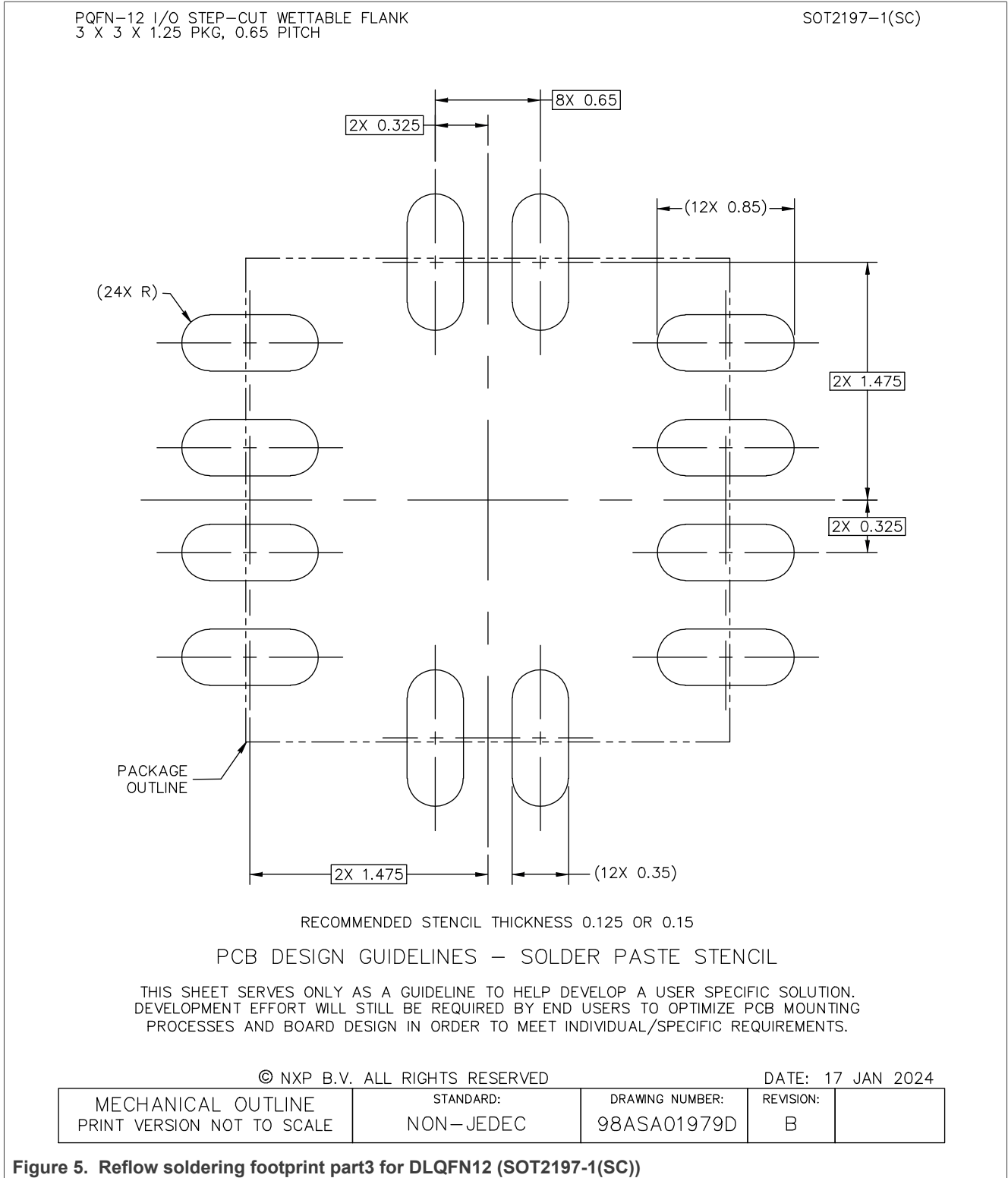


Figure 3. Reflow soldering footprint part1 for DLQFN12 (SOT2197-1(SC))

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PQFN-12 I/O STEP-CUT WETTABLE FLANK  
3 X 3 X 1.25 PKG, 0.65 PITCH

SOT2197-1(SC)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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DATE: 17 JAN 2024

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01979D	REVISION: B	
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Figure 6. Package outline note DLQFN12 (SOT2197-1(SC))

## 4 Legal information

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